

### Features

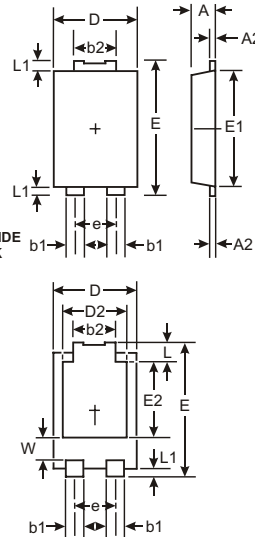
- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- Low Forward Voltage Drop
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Applications
- High Forward Surge Current Capability
- **Lead Free Finish**
- **"Green" Molding Compound (No Br, Sb)**

### Mechanical Data

- Case: PowerDI™5
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Finish – Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 (E3)
- Polarity: See Diagram
- Marking: See Page 3
- Weight: 0.093 grams (approximate)

LEFT PIN ○ RIGHT PIN ○ BOTTOMSIDE HEAT SINK ○

Note: Pins Left & Right must be electrically connected at the printed circuit board.



PowerDI™5		
Dim	Min	Max
A	1.05	1.15
A2	0.33	0.43
b1	0.80	0.99
b2	1.70	1.88
D	3.90	4.05
D2	3.05 NOM	
E	6.40	6.60
e	1.84 NOM	
E1	5.30	5.45
E2	3.55 NOM	
L	0.75	0.95
L1	0.50	0.65
W	1.20	1.50
All Dimensions in mm		

### Maximum Ratings @ T<sub>A</sub> = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	40	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	28	V
Average Rectified Output Current (See also figure 5)	I <sub>O</sub>	5	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave Superimposed on Rated Load	I <sub>FSM</sub>	120	A
Operating Temperature Range	T <sub>j</sub>	-55 to +150	°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C

### Thermal Characteristics @ T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Typ	Max	Unit
Thermal Resistance Junction to Soldering Point	R <sub>θJS</sub>	—	4.0	°C/W
Thermal Resistance Junction to Ambient Air (Note 1)	R <sub>θJA</sub>	95	—	°C/W
Thermal Resistance Junction to Ambient Air (Note 2)	R <sub>θJA</sub>	70	—	°C/W
Thermal Resistance Junction to Ambient Air (Note 3)	R <sub>θJA</sub>	50	—	°C/W

Notes: 1. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com/datasheets/ap02001.pdf>.  
2. Polyimide PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com/datasheets/ap02001.pdf>.  
3. Polyimide PCB, 2 oz. Copper. Cathode pad dimensions 9.4mm x 7.2mm. Anode pad dimensions 2.7mm x 1.6mm.

**Electrical Characteristics** @  $T_A = 25^\circ\text{C}$  unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 4)	$V_{(BR)R}$	40	—	—	V	$I_R = 0.5\text{mA}$
Forward Voltage	$V_F$	—	0.48 0.43 0.57 0.55	0.52 0.47 0.65 0.59	V	$I_F = 5\text{A}, T_S = 25^\circ\text{C}$ $I_F = 5\text{A}, T_S = 125^\circ\text{C}$ $I_F = 10\text{A}, T_S = 25^\circ\text{C}$ $I_F = 10\text{A}, T_S = 125^\circ\text{C}$
Reverse Leakage Current (Note 4)	$I_R$	—	0.015 3 10	0.30 20 40	mA	$T_S = 25^\circ\text{C}, V_R = 40\text{V}$ $T_S = 100^\circ\text{C}, V_R = 40\text{V}$ $T_S = 125^\circ\text{C}, V_R = 40\text{V}$

Notes: 4. Short duration test pulse used to minimize self-heating effect.

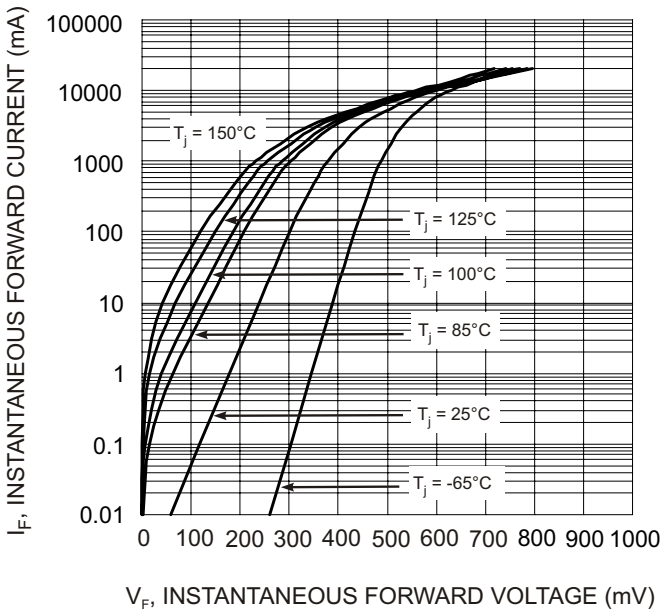


Fig. 1 Typical Forward Characteristics

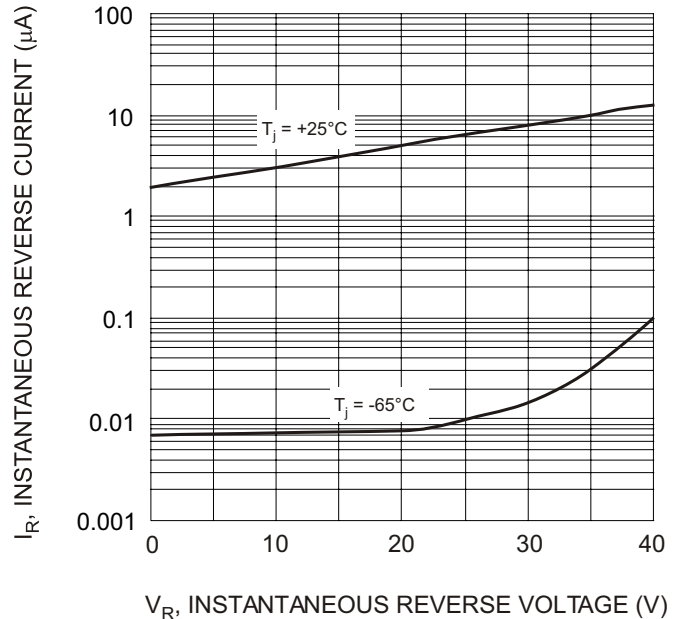


Fig. 2 Typical Reverse Characteristics

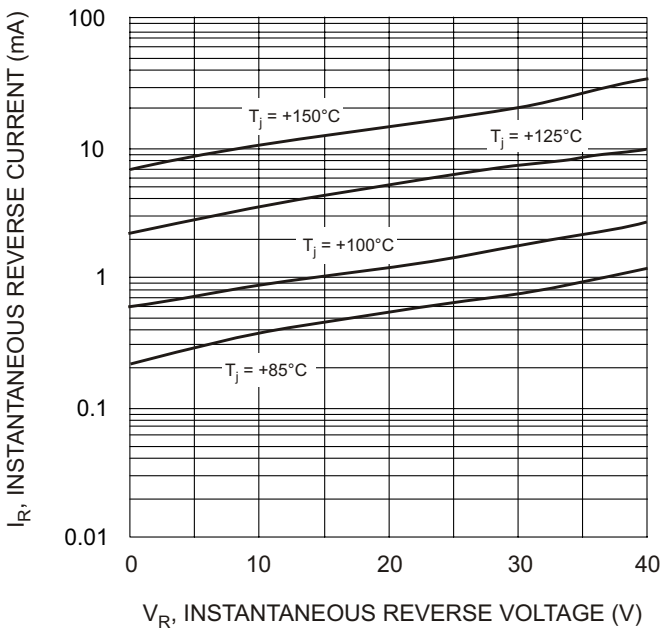


Fig. 3 Typical Reverse Characteristics

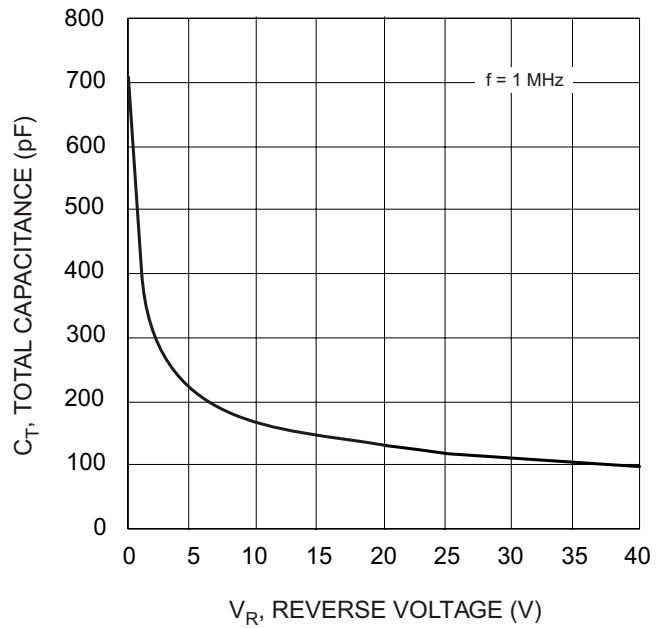
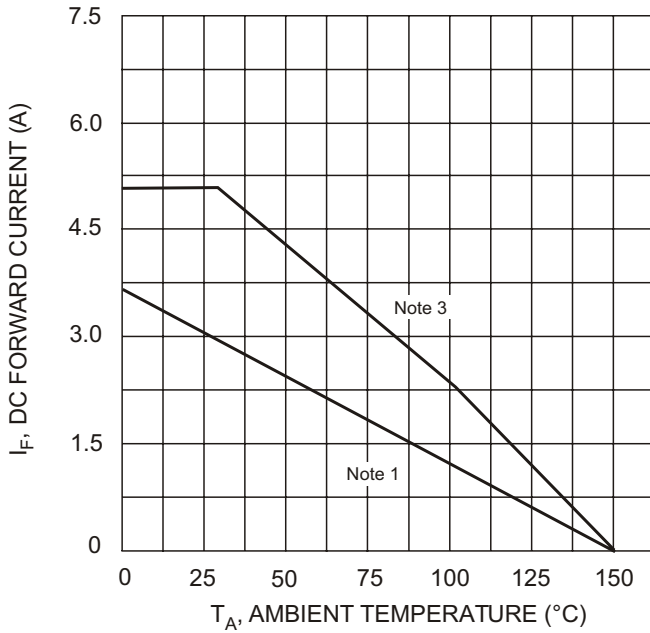
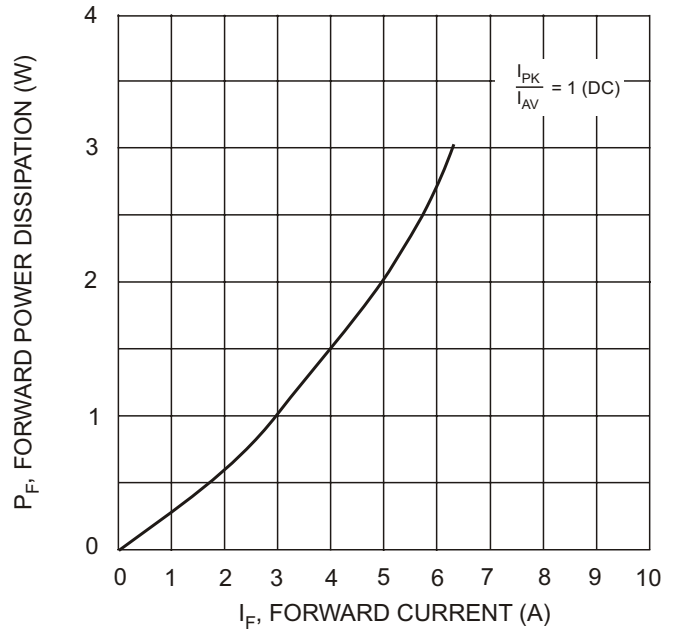


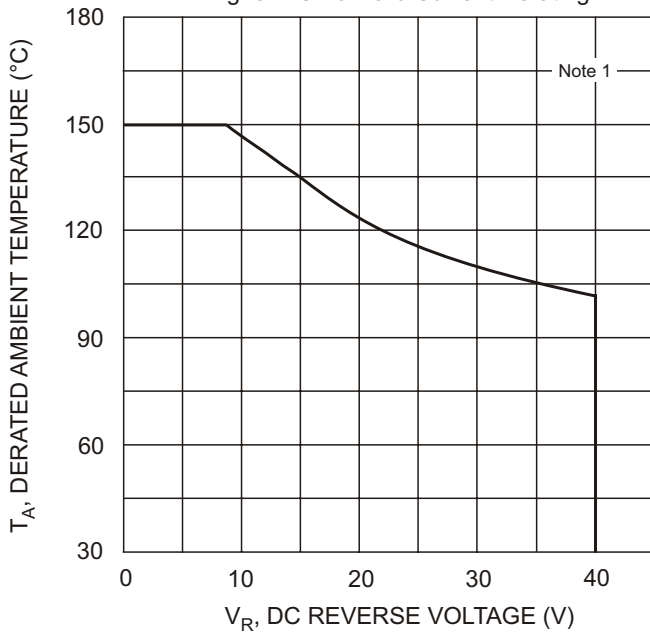
Fig. 4 Typical Total Capacitance vs. Reverse Voltage



$T_A$ , AMBIENT TEMPERATURE (°C)  
Fig. 5 DC Forward Current Derating



$I_F$ , FORWARD CURRENT (A)  
Fig. 6 Forward Power Dissipation



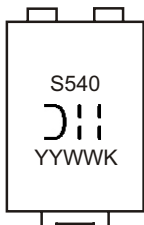
$V_R$ , DC REVERSE VOLTAGE (V)  
Fig. 7 Operating Temperature Derating

**Ordering Information** (Note 5)

Device	Packaging	Shipping
PDS540-13	PowerDI™5	5000/Tape & Reel

- Notes:
- FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com/datasheets/ap02001.pdf>.
  - Polyimide PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com/datasheets/ap02001.pdf>.
  - Polyimide PCB, 2 oz. Copper. Cathode pad dimensions 9.4mm x 7.2mm. Anode pad dimensions 2.7mm x 1.6mm.
  - Short duration test pulse used to minimize self-heating effect.
  - For Packaging Details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

**Marking Information**



S540 = Product type marking code  
 J: = Manufacturers' code marking  
 YYWW = Date code marking  
 YY = Last digit of year ex: 04 for 2004  
 WW = Week code 01 to 52  
 K = Factory Designator

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